

**Amendments to the Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (currently amended) A housing for an integrated circuit, comprising:

a base for securing a substrate with an integrated circuit thereon;

a top cover; and

a body with a cavity for receiving the substrate and at least a portion of the top cover therein to form an enclosed housing therewith, the body including at least one connector extending from within the cavity to outside of the body and configured to physically contact the integrated circuit when the substrate is in the cavity.

2. (original) The housing of claim 1, wherein any one or more of the base, the body, and the top cover comprise a metal.

3. (original) The housing of claim 1, wherein the at least one connector is an RF connector.

4. (original) The housing of claim 1, wherein the at least one connector is a DC connector.

5. (original) The housing of claim 1, wherein each of the base, the body, and the top cover further comprise one or more openings for receiving fasteners therein to secure the base, the body, and the top cover together to form the enclosed housing.

6. (original) The housing of claim 5, further comprising:

one or more fasteners configured to be received in the openings and thereby secure the base, the body, and the top cover together to form the enclosed housing.

7. (original) The housing of claim 1, wherein the top cover further comprises:

an absorber formed of a material that absorbs radio frequency energy, the absorber configured to be received into the cavity when the base, the body, and the top cover are secured together.

8. (original) The housing of claim 1, further comprising:

an integrated circuit mounted onto the base to be received in the cavity and contact the at least one connector when the base, the body, and the top cover are secured together.

9. (original) The housing of claim 8, wherein the integrated circuit is a monolithic microwave integrated circuit.

10. (previously presented) The housing of claim 8, wherein the integrated circuit is secured to the base with indium.

11. (currently amended) A method for forming a housing for an integrated circuit, comprising:

providing a base for securing a substrate with an integrated circuit thereon;

providing a top cover; and

providing a body with a cavity for receiving the substrate and at least a portion of the top cover therein to form an enclosed housing therewith, the body including at least one connector extending from within the cavity to outside of the body and configured to physically contact the integrated circuit when the substrate is in the cavity.

12. (original) The method of claim 11, wherein any one or more of the base, the body, and the top cover comprise a metal.

13. (original) The method of claim 11, wherein the at least one connector is an RF connector.

14. (original) The method of claim 11, wherein the at least one connector is a DC connector.

15. (original) The method of claim 11, wherein each of the base, the body, and the top cover further comprise one or more openings for receiving fasteners therein to secure the base, the body, and the top cover together to form the enclosed housing.

16. (original) The method of claim 15, further comprising:  
providing one or more fasteners configured to be received in the openings and thereby secure the base, the body, and the top cover together to form the enclosed housing.

17. (original) The method of claim 16, further comprising:  
securing the base, the body, and the top cover together with the one or more fasteners to form the enclosed housing.

18. (previously presented) The method of claim 11, wherein the top cover further comprises:

an absorber formed of a material that absorbs radio frequency energy, the absorber configured to be received into the cavity when the base, the body, and the top cover are secured together.

19. (previously presented) The method of claim 11, further comprising:

mounting an integrated circuit onto the base so as to be received in the cavity and contact the at least one connector when the base, the body, and the top cover are secured together.

20. (previously presented) The method of claim 19, wherein the integrated circuit is a monolithic microwave integrated circuit.